100% Material Declaration Data Sheet FFG323

Average Weight: 2.8477 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.000010**	**0.000%**
	Silicon	7440-21-3	100.00		0.000010	
Solder Bump					**0.016860**	**0.592%**
	Tin	7440-31-5	63.00		0.010622	
	Lead	7439-92-1	37.00		0.006238	
Underfill					**0.056000**	**1.966%**
	Silica	60676-86-0	70.00		0.039200	
	Epoxy Resin A	9003-36-5	20.00		0.011200	
	Epoxy Resin B	25068-38-6	3.00		0.001680	
	Hardener	19900-65-3	7.00		0.003920	
Heat Spreader					**1.100000**	**38.627%**
	Copper	7440-50-8	99.60		1.095600	
	Nickel	7440-02-0	0.40		0.004400	
Heat Spreader Adhesive					**0.031000**	**1.089%**
	Organopolysiloxane mixture	N/A	100.00		0.031000	
Substrate					**1.343877**	**47.191%**
	Copper	7440-50-8	47.61	Metal Layer	0.639826	
	Nickel	7440-02-0	0.51	Metal Layer	0.006854	
	Gold	7440-57-5	0.11	Metal Layer	0.001478	
	Glass fiber	N/A	10.35		0.139093	
	Halogen fire retardant	N/A	5.25		0.070500	
	BT (core)	N/A	27.54		0.370148	
	Solder Mask	N/A	8.63		0.115978	
Solder Balls					**0.300000**	**10.535%**
	Tin	7440-31-5	95.50		0.286500	
	Silver	7440-22-4	4.00		0.012000	
	Copper	7440-50-8	0.50		0.001500	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
12/12/07	1.0	Initial release.